



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	C166SV2
Core Size	16-Bit
Speed	20MHz
Connectivity	EBI/EMI, SPI, UART/USART
Peripherals	PWM, WDT
Number of I/O	79
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 2.7V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	PG-TQFP-100-16
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc164n-16f20f-bb

Table of Contents

1	Summary of Features	1
2	General Device Information	4
2.1	Introduction	4
2.2	Pin Configuration and Definition	5
3	Functional Description	14
3.1	Memory Subsystem and Organization	15
3.2	External Bus Controller	17
3.3	Central Processing Unit (CPU)	18
3.4	Interrupt System	20
3.5	On-Chip Debug Support (OCDS)	25
3.6	Capture/Compare Units (CAPCOM1/2)	26
3.7	The Capture/Compare Unit CAPCOM6	29
3.8	General Purpose Timer (GPT12E) Unit	30
3.9	Real Time Clock	33
3.10	Asynchronous/Synchronous Serial Interfaces (ASC0/ASC1)	35
3.11	High Speed Synchronous Serial Channels (SSC0/SSC1)	36
3.12	Watchdog Timer	36
3.13	Clock Generation	37
3.14	Parallel Ports	37
3.15	Power Management	40
3.16	Instruction Set Summary	41
4	Electrical Parameters	43
4.1	Absolute Maximum Ratings	43
4.2	Package Properties	43
4.3	Operating Conditions	44
4.4	Parameter Interpretation	45
4.5	DC Parameters	46
5	Timing Parameters	52
5.1	Definition of Internal Timing	52
5.2	External Clock Drive XTAL1	55
5.3	Testing Waveforms	56
5.4	AC Characteristics	57
6	Packaging	62

General Device Information

Table 2 Pin Definitions and Functions

Symbo l	Pin Num.	Input Outp.	Function
$\overline{\text{RSTIN}}$	1	I	<p>Reset Input with Schmitt-Trigger characteristics. A low level at this pin while the oscillator is running resets the XC164N. A spike filter suppresses input pulses <10 ns. Input pulses >100 ns safely pass the filter. The minimum duration for a safe recognition should be 100 ns + 2 CPU clock cycles.</p> <p><i>Note: The reset duration must be sufficient to let the hardware configuration signals settle.</i></p> <p><i>External circuitry must guarantee low level at the $\overline{\text{RSTIN}}$ pin at least until both power supply voltages have reached the operating range.</i></p>
P20.12	2	IO	For details, please refer to the description of P20 .
$\overline{\text{NMI}}$	3	I	<p>Non-Maskable Interrupt Input. A high to low transition at this pin causes the CPU to vector to the NMI trap routine. When the PWRDN (power down) instruction is executed, the $\overline{\text{NMI}}$ pin must be low in order to force the XC164N into power down mode. If $\overline{\text{NMI}}$ is high, when PWRDN is executed, the part will continue to run in normal mode.</p> <p>If not used, pin $\overline{\text{NMI}}$ should be pulled high externally.</p>
P0H.0- P0H.3	4...7	IO	For details, please refer to the description of PORT0 .

General Device Information
Table 2 Pin Definitions and Functions (cont'd)

Symbo l	Pin Num.	Input Outp.	Function
P9		IO	Port 9 is a 6-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output (configurable as push/pull or open drain driver). The input threshold of Port 9 is selectable (standard or special).
P9.0	10	I/O	The following Port 9 pins also serve for alternate functions: CC16IO CAPCOM2: CC16 Capture Inp./Compare Outp.,
P9.1	11	I I/O	EX7IN Fast External Interrupt 7 Input (alternate pin B) CC17IO CAPCOM2: CC17 Capture Inp./Compare Outp.,
P9.2	12	I I/O	EX6IN Fast External Interrupt 6 Input (alternate pin B) CC18IO CAPCOM2: CC18 Capture Inp./Compare Outp.,
P9.3	13	I I/O	EX7IN Fast External Interrupt 7 Input (alternate pin A) CC19IO CAPCOM2: CC19 Capture Inp./Compare Outp.,
P9.4	14	I I/O	EX6IN Fast External Interrupt 6 Input (alternate pin A) CC20IO CAPCOM2: CC20 Capture Inp./Compare Outp.
P9.5	15	I/O	CC21IO CAPCOM2: CC21 Capture Inp./Compare Outp.
P5		I	Port 5 is a 14-bit input-only port. Some pins of Port 5 serve as timer inputs:
P5.0	18	I	No Alternate Function beside General Purpose Input
P5.1	19	I	No Alternate Function beside General Purpose Input
P5.2	20	I	No Alternate Function beside General Purpose Input
P5.3	21	I	No Alternate Function beside General Purpose Input
P5.4	22	I	No Alternate Function beside General Purpose Input
P5.5	23	I	T6EUD GPT2 Timer T6 Ext. Up/Down Ctrl. Inp.
P5.10	24	I	T5EUD GPT2 Timer T5 Ext. Up/Down Ctrl. Inp.
P5.11	25	I	
P5.6	26	I	
P5.7	27	I	T6IN GPT2 Timer T6 Count/Gate Input
P5.12	30	I	T5IN GPT2 Timer T5 Count/Gate Input
P5.13	31	I	T4EUD GPT1 Timer T4 Ext. Up/Down Ctrl. Inp.
P5.14	32	I	T2EUD GPT1 Timer T2 Ext. Up/Down Ctrl. Inp.
P5.15	33	I	

General Device Information
Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Num.	Input Outp.	Function
P4		IO	Port 4 is an 8-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output (configurable as push/pull or open drain driver). The input threshold of Port 4 is selectable (standard or special). Port 4 can be used to output the segment address lines, the optional chip select lines, and for serial interface lines:
P4.0	53	O	<u>A16</u> Least Significant Segment Address Line,
		O	<u>CS3</u> Chip Select 3 Output
P4.1	54	O	<u>A17</u> Segment Address Line,
		O	<u>CS2</u> Chip Select 2 Output
P4.2	55	O	<u>A18</u> Segment Address Line,
		O	<u>CS1</u> Chip Select 1 Output
P4.3	56	O	<u>A19</u> Segment Address Line,
		O	<u>CS0</u> Chip Select 0 Output
P4.4	57	O	A20 Segment Address Line,
		I	EX5IN Fast External Interrupt 5 Input (alternate pin B)
P4.5	58	O	A21 Segment Address Line,
		I	EX4IN Fast External Interrupt 4 Input (alternate pin B)
P4.6	59	O	A22 Segment Address Line,
		I	EX5IN Fast External Interrupt 5 Input (alternate pin A)
P4.7	60	O	A23 Most Significant Segment Address Line,
		I	EX4IN Fast External Interrupt 4 Input (alternate pin A)

General Device Information
Table 2 Pin Definitions and Functions (cont'd)

Symbo l	Pin Num.	Input Outp.	Function
PORT1 (cont'd)		IO	...continued...
P1H.0	89	I	<u>CC6POS0</u> CAPCOM6: Position 0 Input,
		I	EX0IN Fast External Interrupt 0 Input (default pin),
		I/O	<u>CC23IO</u> CAPCOM2: CC23 Capture Inp./Compare Outp.
P1H.1	90	I	<u>CC6POS1</u> CAPCOM6: Position 1 Input,
		I	EX1IN Fast External Interrupt 1 Input (default pin),
		I/O	<u>MRST1</u> SSC1 Master-Receive/Slave-Transmit In/Out.
P1H.2	91	I	<u>CC6POS2</u> CAPCOM6: Position 2 Input,
		I	EX2IN Fast External Interrupt 2 Input (default pin),
		I/O	MTSR1 SSC1 Master-Transmit/Slave-Receive Out/Inp.
P1H.3	92	I	T7IN CAPCOM2: Timer T7 Count Input,
		I/O	SCLK1 SSC1 Master Clock Output / Slave Clock Input,
		I	EX3IN Fast External Interrupt 3 Input (default pin),
		I	EX0IN Fast External Interrupt 0 Input (alternate pin A)
P1H.4	93	I/O	<u>CC24IO</u> CAPCOM2: CC24 Capture Inp./Compare Outp.,
		I	EX4IN Fast External Interrupt 4 Input (default pin)
P1H.5	94	I/O	<u>CC25IO</u> CAPCOM2: CC25 Capture Inp./Compare Outp.,
		I	EX5IN Fast External Interrupt 5 Input (default pin)
P1H.6	95	I/O	<u>CC26IO</u> CAPCOM2: CC26 Capture Inp./Compare Outp.,
		I	EX6IN Fast External Interrupt 6 Input (default pin)
P1H.7	96	I/O	<u>CC27IO</u> CAPCOM2: CC27 Capture Inp./Compare Outp.,
		I	EX7IN Fast External Interrupt 7 Input (default pin)
<u>XTAL2</u>	99	O	XTAL2: Output of the oscillator amplifier circuit
<u>XTAL1</u>	100	I	XTAL1: Input to the oscillator amplifier and input to the internal clock generator To clock the device from an external source, drive XTAL1, while leaving XTAL2 unconnected. Minimum and maximum high/low and rise/fall times specified in the AC Characteristics must be observed.
res	28	-	pin is reserved and connected to V_{DDP}
res	29	-	pin is reserved and connected to V_{SSP}
V_{DDI}	35, 97	-	Digital Core Supply Voltage (On-Chip Modules): +2.5 V during normal operation and idle mode. Please refer to the Operating Conditions

General Device Information

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Num.	Input Outp.	Function
V_{DDP}	9, 17, 38, 61, 87	-	Digital Pad Supply Voltage (Pin Output Drivers): +5 V during normal operation and idle mode. Please refer to the Operating Conditions
V_{SSI}	34, 98	-	Digital Ground.
V_{SSP}	8, 16, 37, 62, 88	-	Connect decoupling capacitors to adjacent V_{DD}/V_{SS} pin pairs as close as possible to the pins. All V_{SS} pins must be connected to the ground-line or ground-plane.

3.2 External Bus Controller

All of the external memory accesses are performed by a particular on-chip External Bus Controller (EBC). It can be programmed either to Single Chip Mode when no external memory is required, or to one of four different external memory access modes¹⁾, which are as follows:

- 16 ... 24-bit Addresses, 16-bit Data, Demultiplexed
- 16 ... 24-bit Addresses, 16-bit Data, Multiplexed
- 16 ... 24-bit Addresses, 8-bit Data, Multiplexed
- 16 ... 24-bit Addresses, 8-bit Data, Demultiplexed

In the demultiplexed bus modes, addresses are output on PORT1 and data is input/output on PORT0 or P0L, respectively. In the multiplexed bus modes both addresses and data use PORT0 for input/output. The high order address (segment) lines use Port 4. The number of active segment address lines is selectable, restricting the external address space to 8 Mbytes ... 64 Kbytes. This is required when interface lines are assigned to Port 4.

Up to 4 external $\overline{\text{CS}}$ signals (3 windows plus default) can be generated in order to save external glue logic. External modules can directly be connected to the common address/data bus and their individual select lines.

Important timing characteristics of the external bus interface have been made programmable (via registers TCONCSx/FCONCSx) to allow the user the adaption of a wide range of different types of memories and external peripherals.

In addition, up to 4 independent address windows may be defined (via registers ADDRSELx) which control the access to different resources with different bus characteristics. These address windows are arranged hierarchically where window 4 overrides window 3, and window 2 overrides window 1. All accesses to locations not covered by these 4 address windows are controlled by TCONCS0/FCONCS0. The currently active window can generate a chip select signal.

The external bus timing is related to the rising edge of the reference clock output CLKOUT. The external bus protocol is compatible with that of the standard C166 Family.

The EBC also controls accesses to resources connected to the on-chip LXBus. The LXBus is an internal representation of the external bus and allows accessing integrated peripherals and modules in the same way as external components.

1) Bus modes are switched dynamically if several address windows with different mode settings are used.

3.4 Interrupt System

With an interrupt response time of typically 8 CPU clocks (in case of internal program execution), the XC164N is capable of reacting very fast to the occurrence of non-deterministic events.

The architecture of the XC164N supports several mechanisms for fast and flexible response to service requests that can be generated from various sources internal or external to the microcontroller. Any of these interrupt requests can be programmed to being serviced by the Interrupt Controller or by the Peripheral Event Controller (PEC).

In contrast to a standard interrupt service where the current program execution is suspended and a branch to the interrupt vector table is performed, just one cycle is 'stolen' from the current CPU activity to perform a PEC service. A PEC service implies a single byte or word data transfer between any two memory locations with an additional increment of either the PEC source, or the destination pointer, or both. An individual PEC transfer counter is implicitly decremented for each PEC service except when performing in the continuous transfer mode. When this counter reaches zero, a standard interrupt is performed to the corresponding source related vector location. PEC services are very well suited, for example, for supporting the transmission or reception of blocks of data. The XC164N has 8 PEC channels each of which offers such fast interrupt-driven data transfer capabilities.

A separate control register which contains an interrupt request flag, an interrupt enable flag and an interrupt priority bitfield exists for each of the possible interrupt nodes. Via its related register, each node can be programmed to one of sixteen interrupt priority levels. Once having been accepted by the CPU, an interrupt service can only be interrupted by a higher prioritized service request. For the standard interrupt processing, each of the possible interrupt nodes has a dedicated vector location.

Fast external interrupt inputs are provided to service external interrupts with high precision requirements. These fast interrupt inputs feature programmable edge detection (rising edge, falling edge, or both edges).

Software interrupts are supported by means of the 'TRAP' instruction in combination with an individual trap (interrupt) number.

Table 4 shows all of the possible XC164N interrupt sources and the corresponding hardware-related interrupt flags, vectors, vector locations and trap (interrupt) numbers.

Note: Interrupt nodes which are not assigned to peripherals (unassigned nodes), may be used to generate software controlled interrupt requests by setting the respective interrupt request bit (xIR).

Functional Description
Table 4 XC164N Interrupt Nodes (cont'd)

Source of Interrupt or PEC Service Request	Control Register	Vector Location ¹⁾	Trap Number
CAPCOM6 Timer T13	CCU6_T13IC	xx'0138 _H	4E _H / 78 _D
CAPCOM6 Emergency	CCU6_EIC	xx'013C _H	4F _H / 79 _D
CAPCOM6	CCU6_IC	xx'0140 _H	50 _H / 80 _D
SSC1 Transmit	SSC1_TIC	xx'0144 _H	51 _H / 81 _D
SSC1 Receive	SSC1_RIC	xx'0148 _H	52 _H / 82 _D
SSC1 Error	SSC1_EIC	xx'014C _H	53 _H / 83 _D
Unassigned node	---	xx'0150 _H	54 _H / 84 _D
Unassigned node	---	xx'0154 _H	55 _H / 85 _D
Unassigned node	---	xx'0158 _H	56 _H / 86 _D
Unassigned node	---	xx'015C _H	57 _H / 87 _D
Unassigned node	---	xx'0164 _H	59 _H / 89 _D
Unassigned node	---	xx'0168 _H	5A _H / 90 _D
Unassigned node	---	xx'016C _H	5B _H / 91 _D
Unassigned node	---	xx'0170 _H	5C _H / 92 _D
Unassigned node	---	xx'0174 _H	5D _H / 93 _D
Unassigned node	---	xx'0100 _H	40 _H / 64 _D
Unassigned node	---	xx'0104 _H	41 _H / 65 _D
Unassigned node	---	xx'012C _H	4B _H / 75 _D
Unassigned node	---	xx'00FC _H	3F _H / 63 _D
Unassigned node	---	xx'0160 _H	58 _H / 88 _D

- 1) Register VECSEG defines the segment where the vector table is located to.
 Bitfield VECSC in register CPUCON1 defines the distance between two adjacent vectors. This table represents the default setting, with a distance of 4 (two words) between two vectors.
- 2) The interrupt nodes assigned to ASC1 are only available in derivatives including the ASC1. Otherwise, they are unassigned nodes.

Functional Description

The XC164N also provides an excellent mechanism to identify and to process exceptions or error conditions that arise during run-time, so-called 'Hardware Traps'. Hardware traps cause immediate non-maskable system reaction which is similar to a standard interrupt service (branching to a dedicated vector table location). The occurrence of a hardware trap is additionally signified by an individual bit in the trap flag register (TFR). Except when another higher prioritized trap service is in progress, a hardware trap will interrupt any actual program execution. In turn, hardware trap services can normally not be interrupted by standard or PEC interrupts.

Table 5 shows all of the possible exceptions or error conditions that can arise during run-time:

Table 5 Hardware Trap Summary

Exception Condition	Trap Flag	Trap Vector	Vector Location ¹⁾	Trap Number	Trap Priority
Reset Functions: – Hardware Reset – Software Reset – W-dog Timer Overflow	–	RESET RESET RESET	xx'0000 _H xx'0000 _H xx'0000 _H	00 _H 00 _H 00 _H	III III III
Class A Hardware Traps: – Non-Maskable Interrupt – Stack Overflow – Stack Underflow – Software Break	NMI STKOF STKUF SOFTBRK	NMITRAP STOTRAP STUTRAP SBRKTRAP	xx'0008 _H xx'0010 _H xx'0018 _H xx'0020 _H	02 _H 04 _H 06 _H 08 _H	II II II II
Class B Hardware Traps: – Undefined Opcode – PMI Access Error – Protected Instruction Fault – Illegal Word Operand Access	UNDOPC PACER PRTFLT ILLOPA	BTRAP BTRAP BTRAP BTRAP	xx'0028 _H xx'0028 _H xx'0028 _H xx'0028 _H	0A _H 0A _H 0A _H 0A _H	I I I I
Reserved	–	–	[2C _H – 3C _H]	[0B _H – 0F _H]	–
Software Traps – TRAP Instruction	–	–	Any [xx'0000 _H – xx'01FC _H] in steps of 4 _H	Any [00 _H – 7F _H]	Current CPU Priority

1) Register VECSEG defines the segment where the vector table is located to.

3.5 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system provides a broad range of debug and emulation features built into the XC164N. The user software running on the XC164N can thus be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface, consisting of the IEEE-1149-conforming JTAG port and a break interface. The debugger controls the OCDS via a set of dedicated registers accessible via the JTAG interface. Additionally, the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported as well as the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU-halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the JTAG interface or via the external bus interface for increased performance.

The debug interface uses a set of 6 interface signals (4 JTAG lines, 2 break lines) to communicate with external circuitry. These interface signals are realized as alternate functions on Port 3 pins.

Complete system emulation is supported by the New Emulation Technology (NET) interface. Via this full-featured emulation interface (including internal buses, control, status, and pad signals) the XC164N chip can be connected to a NET carrier chip.

The use of the XC164N production chip together with the carrier chip provides superior emulation behavior, because the emulation system shows exactly the same functionality as the production chip (use of the identical silicon).

3.7 The Capture/Compare Unit CAPCOM6

The CAPCOM6 unit supports generation and control of timing sequences on up to three 16-bit capture/compare channels plus one independent 10-bit compare channel.

In compare mode the CAPCOM6 unit provides two output signals per channel which have inverted polarity and non-overlapping pulse transitions (deadtime control). The compare channel can generate a single PWM output signal and is further used to modulate the capture/compare output signals.

In capture mode the contents of compare timer T12 is stored in the capture registers upon a signal transition at pins CCx.

Compare timers T12 (16-bit) and T13 (10-bit) are free running timers which are clocked by the prescaled system clock.

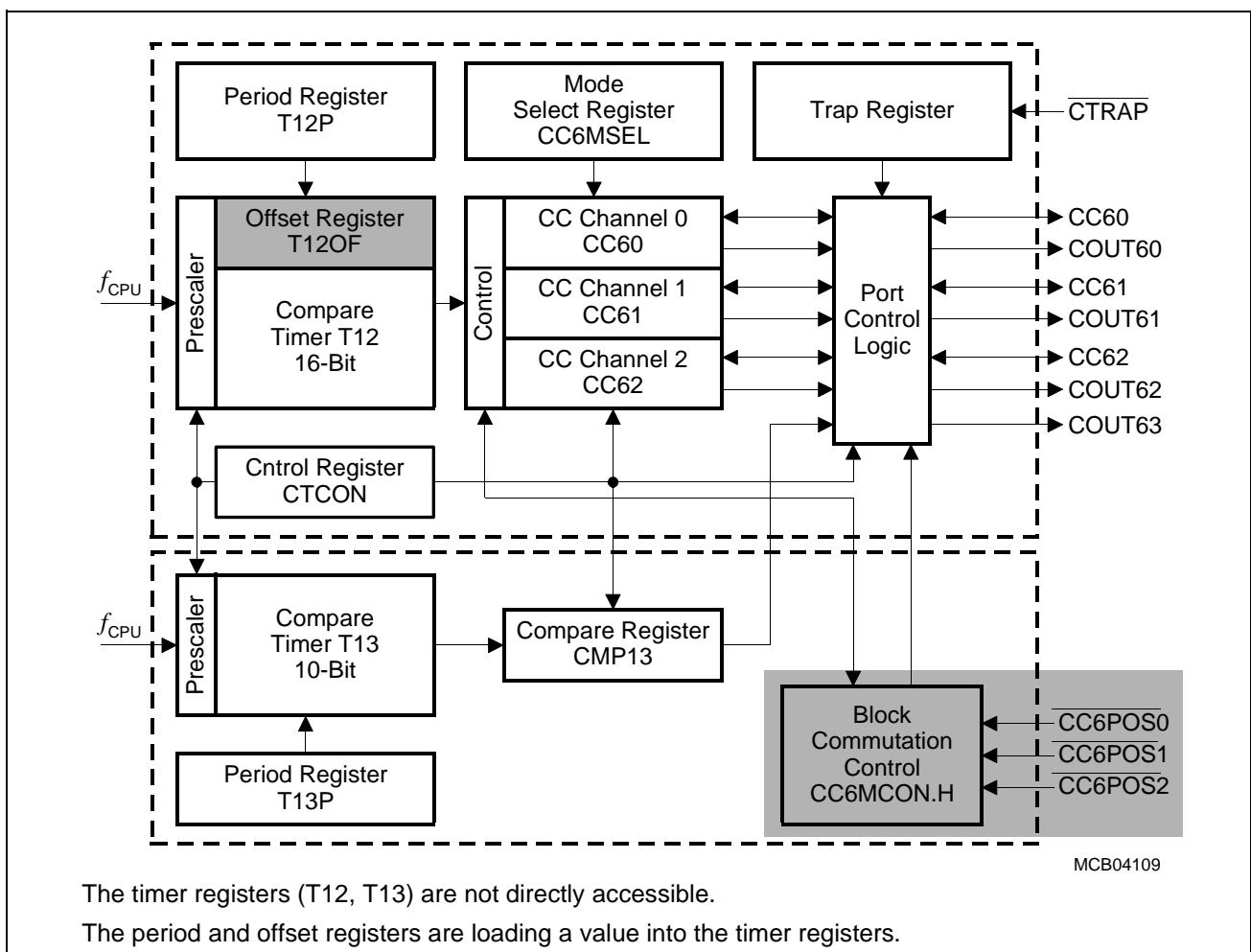


Figure 6 CAPCOM6 Block Diagram

For motor control applications both subunits may generate versatile multichannel PWM signals which are basically either controlled by compare timer T12 or by a typical hall sensor pattern at the interrupt inputs (block commutation).

Functional Description

3.16 Instruction Set Summary

Table 8 lists the instructions of the XC164N in a condensed way.

The various addressing modes that can be used with a specific instruction, the operation of the instructions, parameters for conditional execution of instructions, and the opcodes for each instruction can be found in the “**Instruction Set Manual**”.

This document also provides a detailed description of each instruction.

Table 8 Instruction Set Summary

Mnemonic	Description	Bytes
ADD(B)	Add word (byte) operands	2 / 4
ADDC(B)	Add word (byte) operands with Carry	2 / 4
SUB(B)	Subtract word (byte) operands	2 / 4
SUBC(B)	Subtract word (byte) operands with Carry	2 / 4
MUL(U)	(Un)Signed multiply direct GPR by direct GPR (16-16-bit)	2
DIV(U)	(Un)Signed divide register MDL by direct GPR (16-/16-bit)	2
DIVL(U)	(Un)Signed long divide reg. MD by direct GPR (32-/16-bit)	2
CPL(B)	Complement direct word (byte) GPR	2
NEG(B)	Negate direct word (byte) GPR	2
AND(B)	Bitwise AND, (word/byte operands)	2 / 4
(X)OR(B)	Bitwise (exclusive)OR, (word/byte operands)	2 / 4
BCLR / BSET	Clear/Set direct bit	2
BMOV(N)	Move (negated) direct bit to direct bit	4
BAND / BOR / BXOR	AND/OR/XOR direct bit with direct bit	4
BCMP	Compare direct bit to direct bit	4
BFLDH / BFLDL	Bitwise modify masked high/low byte of bit-addressable direct word memory with immediate data	4
CMP(B)	Compare word (byte) operands	2 / 4
CMPD1/2	Compare word data to GPR and decrement GPR by 1/2	2 / 4
CMPI1/2	Compare word data to GPR and increment GPR by 1/2	2 / 4
PRIOR	Determine number of shift cycles to normalize direct word GPR and store result in direct word GPR	2
SHL / SHR	Shift left/right direct word GPR	2
ROL / ROR	Rotate left/right direct word GPR	2
ASHR	Arithmetic (sign bit) shift right direct word GPR	2
MOV(B)	Move word (byte) data	2 / 4
MOVBS/Z	Move byte operand to word op. with sign/zero extension	2 / 4

Electrical Parameters

4.3 Operating Conditions

The following operating conditions must not be exceeded to ensure correct operation of the XC164N. All parameters specified in the following sections refer to these operating conditions, unless otherwise noticed.

Table 11 Operating Condition Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Digital supply voltage for the core	V_{DDI}	2.35	2.7	V	Active mode, $f_{CPU} = f_{CPUmax}^{1)}$
Digital supply voltage for IO pads	V_{DDP}	4.4	5.5	V	Active mode 2) 3)
Supply Voltage Difference	ΔV_{DD}	-0.5	–	V	$V_{DDP} - V_{DDI}^{4)}$
Digital ground voltage	V_{SS}	0		V	Reference voltage
Overload current	I_{OV}	-5	5	mA	Per IO pin ⁵⁾⁶⁾
		-2	5	mA	Per analog input pin ⁵⁾⁶⁾
Overload current coupling factor for analog inputs ⁷⁾	K_{OVA}	–	1.0×10^{-4}	–	$I_{OV} > 0$
		–	1.5×10^{-3}	–	$I_{OV} < 0$
Overload current coupling factor for digital I/O pins ⁷⁾	K_{OVD}	–	5.0×10^{-3}	–	$I_{OV} > 0$
		–	1.0×10^{-2}	–	$I_{OV} < 0$
Absolute sum of overload currents	$\Sigma I_{OV} $	–	50	mA	⁶⁾
External Load Capacitance	C_L	–	50	pF	Pin drivers in default mode ⁸⁾
Ambient temperature	T_A	0	70	°C	SAB-XC164N ...
		-40	85	°C	SAF-XC164N ...
		-40	125	°C	SAK-XC164N ...

1) $f_{CPUmax} = 40$ MHz for devices marked ...40F, $f_{CPUmax} = 20$ MHz for devices marked ...20F.

2) External circuitry must guarantee low level at the RSTIN pin at least until both power supply voltages have reached the operating level.

3) The specified voltage range is allowed for operation. The range limits may be reached under extreme operating conditions. However, specified parameters, such as leakage currents, refer to the standard operating voltage range of $V_{DDP} = 4.75$ V to 5.25 V.

4) This limitation must be fulfilled under all operating conditions including power-ramp-up, power-ramp-down, and power-save modes.

Electrical Parameters
4.5 DC Parameters
DC Characteristics

(Operating Conditions apply)¹⁾

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input low voltage TTL (all except XTAL1)	V_{IL} SR	-0.5	$0.2 \times V_{DDP} - 0.1$	V	–
Input low voltage XTAL1	V_{ILC} SR	-0.5	$0.3 \times V_{DDI}$	V	–
Input low voltage (Special Threshold)	V_{ILS} SR	-0.5	$0.45 \times V_{DDP}$	V	²⁾
Input high voltage TTL (all except XTAL1)	V_{IH} SR	$0.2 \times V_{DDP} + 0.9$	$V_{DDP} + 0.5$	V	–
Input high voltage XTAL1	V_{IHC} SR	$0.7 \times V_{DDI}$	$V_{DDI} + 0.5$	V	–
Input high voltage (Special Threshold)	V_{IHS} SR	$0.8 \times V_{DDP} - 0.2$	$V_{DDP} + 0.5$	V	²⁾
Input Hysteresis (Special Threshold)	HYS	$0.04 \times V_{DDP}$	–	V	V_{DDP} in [V], Series resistance = 0Ω ²⁾
Output low voltage	V_{OL} CC	–	1.0	V	$I_{OL} \leq I_{OLmax}$ ³⁾
		–	0.45	V	$I_{OL} \leq I_{OLnom}$ ^{3) 4)}
Output high voltage ⁵⁾	V_{OH} CC	$V_{DDP} - 1.0$	–	V	$I_{OH} \geq I_{OHmax}$ ³⁾
		$V_{DDP} - 0.45$	–	V	$I_{OH} \geq I_{OHnom}$ ^{3) 4)}
Input leakage current (Port 5) ⁶⁾	I_{OZ1} CC	–	± 300	nA	$0 \text{ V} < V_{IN} < V_{DDP}$, $T_A \leq 125^\circ \text{C}$
			± 200	nA	$0 \text{ V} < V_{IN} < V_{DDP}$, $T_A \leq 85^\circ \text{C}$ ¹²⁾
Input leakage current (all other) ⁶⁾	I_{OZ2} CC	–	± 500	nA	$0.45 \text{ V} < V_{IN} < V_{DDP}$
Configuration pull-up current ⁷⁾	I_{CPUH} ⁸⁾	–	-10	μA	$V_{IN} = V_{IHmin}$
	I_{CPUL} ⁹⁾	-100	–	μA	$V_{IN} = V_{ILmax}$

Electrical Parameters
DC Characteristics (cont'd)
 (Operating Conditions apply)¹⁾

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Configuration pull-down current ¹⁰⁾	$I_{CPDL}^{8)}$	–	10	μA	$V_{IN} = V_{ILmax}$
	$I_{CPDH}^{9)}$	120	–	μA	$V_{IN} = V_{IHmin}$
Level inactive hold current ¹¹⁾	$I_{LHI}^{8)}$	–	-10	μA	$V_{OUT} = 0.5 \times V_{DDP}$
Level active hold current ¹¹⁾	$I_{LHA}^{9)}$	-100	–	μA	$V_{OUT} = 0.45 V$
XTAL1 input current	I_{IL} CC	–	±20	μA	$0 V < V_{IN} < V_{DDI}$
Pin capacitance ¹²⁾ (digital inputs/outputs)	C_{IO} CC	–	10	pF	

- 1) Keeping signal levels within the limits specified in this table, ensures operation without overload conditions. For signal levels outside these specifications, also refer to the specification of the overload current I_{OV} .
- 2) This parameter is tested for P2, P3, P4, P9.
- 3) The maximum deliverable output current of a port driver depends on the selected output driver mode, see [Table 12, Current Limits for Port Output Drivers](#). The limit for pin groups must be respected.
- 4) As a rule, with decreasing output current the output levels approach the respective supply level ($V_{OL} \rightarrow V_{SS}$, $V_{OH} \rightarrow V_{DDP}$). However, only the levels for nominal output currents are guaranteed.
- 5) This specification is not valid for outputs which are switched to open drain mode. In this case the respective output will float and the voltage results from the external circuitry.
- 6) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. Please refer to the definition of the overload coupling factor K_{OV} .
- 7) This specification is valid during Reset for configuration on \overline{RD} , \overline{WR} , \overline{EA} , PORT0.
- 8) The maximum current may be drawn while the respective signal line remains inactive.
- 9) The minimum current must be drawn to drive the respective signal line active.
- 10) This specification is valid during Reset for configuration on ALE.
- 11) This specification is valid during Reset for pins P4.3-0, which can act as \overline{CS} outputs.
- 12) Not subject to production test - verified by design/characterization.

Electrical Parameters
Table 12 Current Limits for Port Output Drivers

Port Output Driver Mode	Maximum Output Current (I_{OLmax} , $-I_{OHmax}$) ¹⁾	Nominal Output Current (I_{OLnom} , $-I_{OHnom}$)
Strong driver	10 mA	2.5 mA
Medium driver	4.0 mA	1.0 mA
Weak driver	0.5 mA	0.1 mA

- 1) An output current above $|I_{OXnom}|$ may be drawn from up to three pins at the same time.
For any group of 16 neighboring port output pins the total output current in each direction (ΣI_{OL} and ΣI_{OH}) must remain below 50 mA.

Power Consumption XC164N
(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Power supply current (active) with all peripherals active	I_{DDI}	–	15 + $2.6 \times f_{CPU}$	mA	¹⁾ f_{CPU} in [MHz] ²⁾
Pad supply current	I_{DDP}	–	5	mA	³⁾
Idle mode supply current with all peripherals active	I_{IDX}	–	15 + $1.2 \times f_{CPU}$	mA	f_{CPU} in [MHz] ²⁾
Sleep and Power-down mode supply current caused by leakage ⁴⁾	I_{PDL} ⁵⁾	–	128,000 $\times e^{-\alpha}$	mA	$V_{DDI} = V_{DDImax}$ ⁶⁾ T_J in [°C] $\alpha = 4670 / (273 + T_J)$
Sleep and Power-down mode supply current caused by leakage and the RTC running, clocked by the main oscillator ⁴⁾	I_{PDM} ⁷⁾	–	0.6 + $0.02 \times f_{OSC}$ + I_{PDL}	mA	$V_{DDI} = V_{DDImax}$ f_{OSC} in [MHz]

- 1) During Flash programming or erase operations the supply current is increased by max. 5 mA.
2) The supply current is a function of the operating frequency. This dependency is illustrated in [Figure 10](#).
These parameters are tested at V_{DDImax} and maximum CPU clock frequency with all outputs disconnected and all inputs at V_{IL} or V_{IH} .
3) The pad supply voltage pins (V_{DDP}) mainly provides the current consumed by the pin output drivers. A small amount of current is consumed even though no outputs are driven, because the drivers' input stages are switched and also the Flash module draws some power from the V_{DDP} supply.
4) The total supply current in Sleep and Power-down mode is the sum of the temperature dependent leakage current and the frequency dependent current for RTC and main oscillator (if active).

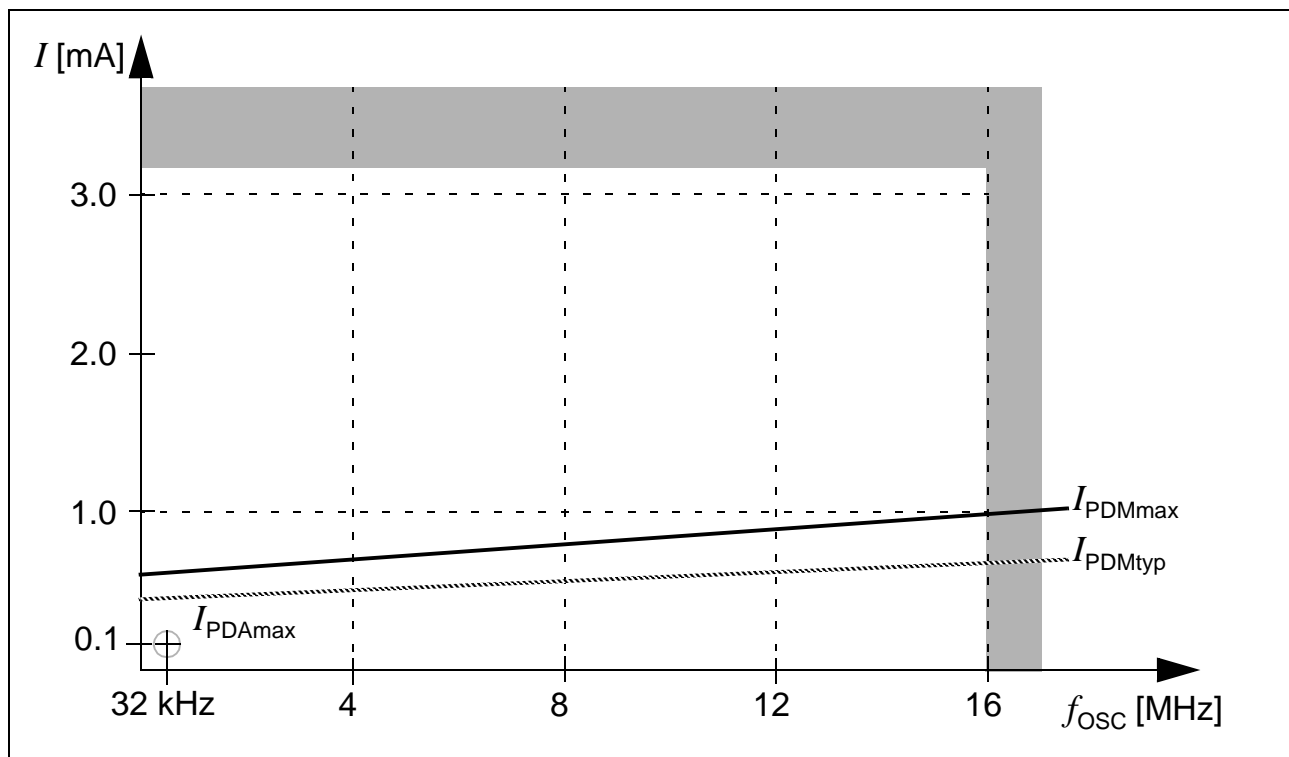


Figure 11 Sleep and Power Down Supply Current due to RTC and Oscillator running, as a Function of Oscillator Frequency

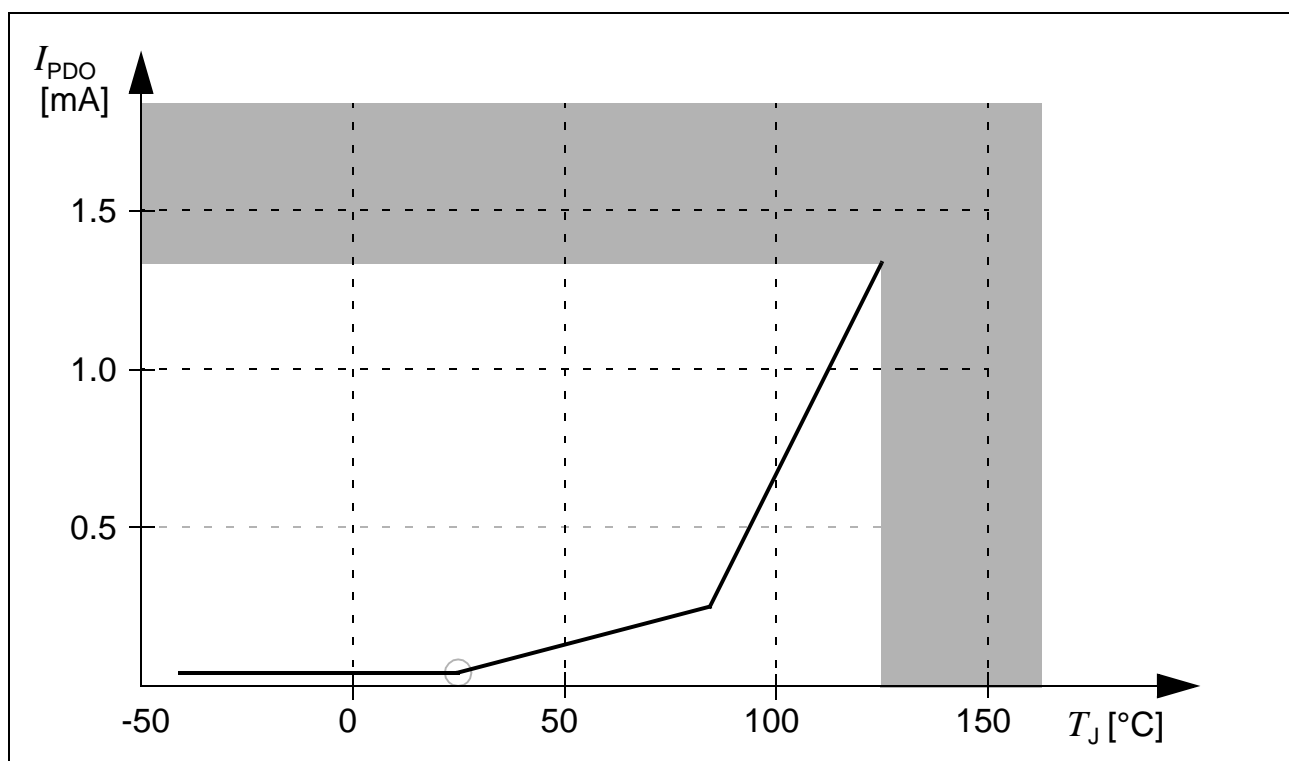


Figure 12 Sleep and Power Down Leakage Supply Current as a Function of Temperature

5 Timing Parameters

5.1 Definition of Internal Timing

The internal operation of the XC164N is controlled by the internal master clock f_{MC} .

The master clock signal f_{MC} can be generated from the oscillator clock signal f_{OSC} via different mechanisms. The duration of master clock periods (TCMs) and their variation (and also the derived external timing) depend on the used mechanism to generate f_{MC} . This influence must be regarded when calculating the timings for the XC164N.

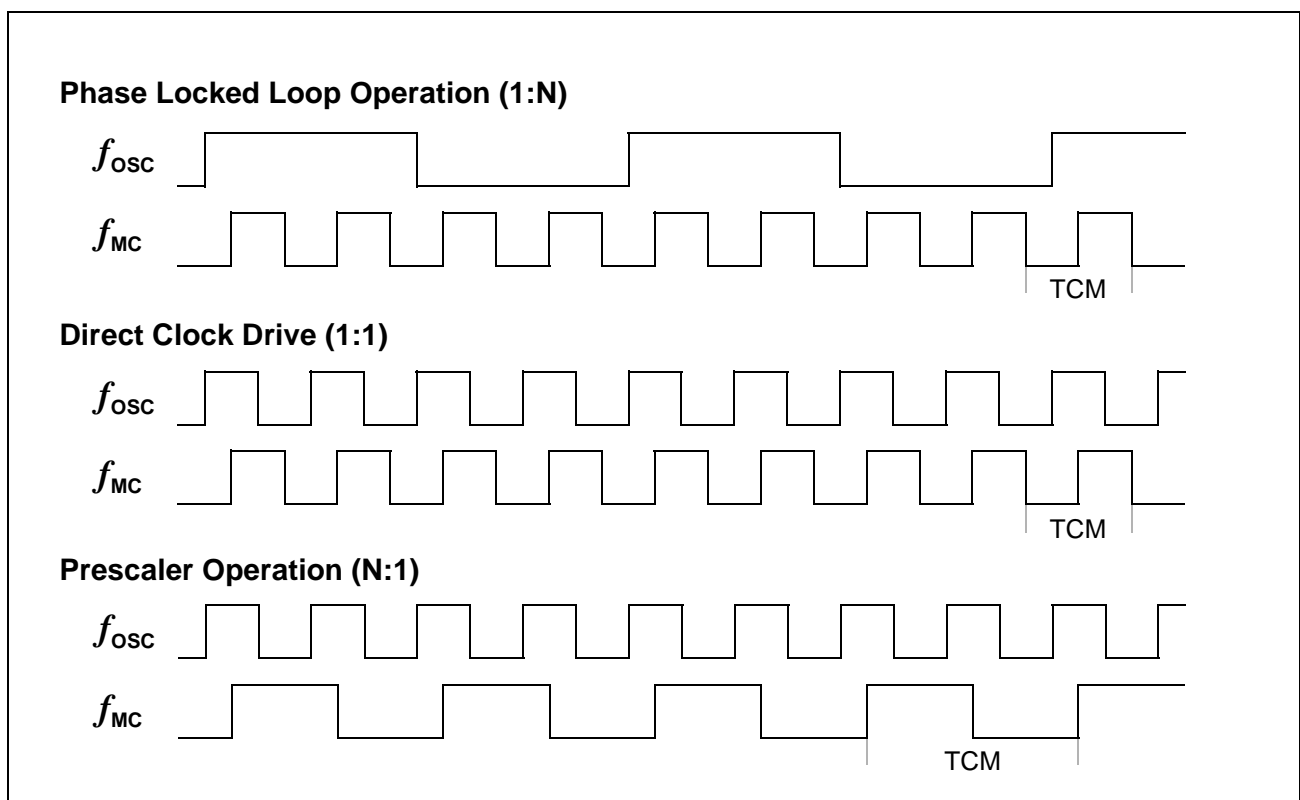


Figure 13 Generation Mechanisms for the Master Clock

Note: The example for PLL operation shown in [Figure 13](#) refers to a PLL factor of 1:4, the example for prescaler operation refers to a divider factor of 2:1.

The used mechanism to generate the master clock is selected by register PLLCON.

CPU and EBC are clocked with the CPU clock signal f_{CPU} . The CPU clock can have the same frequency as the master clock ($f_{CPU} = f_{MC}$) or can be the master clock divided by two: $f_{CPU} = f_{MC} / 2$. This factor is selected by bit CPSYS in register SYSCON1.

The specification of the external timing (AC Characteristics) depends on the period of the CPU clock, called "TCP".

The other peripherals are supplied with the system clock signal f_{SYS} which has the same frequency as the CPU clock signal f_{CPU} .

Timing Parameters
Table 17 External Bus Cycle Timing (Operating Conditions apply)

Parameter	Symbol		Limits		Unit
			min.	max.	
Output valid delay for: RD, WR(L/H)	t_{c10}	CC	1	15	ns
Output valid delay for: BHE, ALE	t_{c11}	CC	-1	8	ns
Output valid delay for: A23...A16, A15...A0 (on PORT1)	t_{c12}	CC	3	18	ns
Output valid delay for: A15...A0 (on PORT0)	t_{c13}	CC	3	18	ns
Output valid delay for: CS	t_{c14}	CC	3	16	ns
Output valid delay for: D15...D0 (write data, mux-mode)	t_{c15}	CC	3	19	ns
Output valid delay for: D15...D0 (write data, demux-mode)	t_{c16}	CC	2	16	ns
Output hold time for: RD, WR(L/H)	t_{c20}	CC	-3	4	ns
Output hold time for: BHE, ALE	t_{c21}	CC	0	11	ns
Output hold time for: A23...A16, A15...A0 (on PORT0)	t_{c23}	CC	1	13	ns
Output hold time for: CS	t_{c24}	CC	-2	4	ns
Output hold time for: D15...D0 (write data)	t_{c25}	CC	1	13	ns
Input setup time for: D15...D0 (read data)	t_{c30}	SR	29	—	ns
Input hold time D15...D0 (read data) ¹⁾	t_{c31}	SR	-5	—	ns

1) Read data are latched with the same (internal) clock edge that triggers the address change and the rising edge of RD. Therefore address changes before the end of RD have no impact on (demultiplexed) read cycles. Read data can be removed after the rising edge of RD

*Note: The shaded parameters have been verified by characterization.
They are not subject to production test.*